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JOINT INDUSTRY STANDARD

Solderability Tests for Component Leads, Terminations, Lugs, Terminals and Wires

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EIA/IPC/JEDEC J-STD-002E

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A joint standard developed by IPC Component and Wire Solderability Specification Task Group (5-23b) of the Assembly and Joining Processes Committee (5-20), the Electronic Components Industry Association Soldering Technology Committee (STC) and the JEDEC Solid State Technology Association Committee (JC14.1)

Users of this publication are encouraged to participate in the development of future revisions.

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